

This listing of claims replaces all prior versions, and listings of claims in the instant application:

Listing of Claims:

1. (canceled)

2. (currently amended) The package of Claim 4 13 further comprising a second electronic component coupled within said pocket.

3. (currently amended) The package of Claim 4 13 wherein said first electronic component is coupled within said pocket in a configuration selected from the group consisting of a wirebond configuration, a surface mount configuration and a flip chip configuration.

4. (currently amended) The package of Claim 4 13 wherein said substrate further comprises:

a pocket base surface; and

a pocket sidewall surface, said pocket base surface and said pocket sidewall surface defining said pocket.

5. (original) The package of Claim 4 wherein said first electronic component comprises a first surface comprising a bond pad and a second surface coupled to said pocket base surface, said package further comprising:

a pin extending through said pocket base surface and through said substrate and protruding from a lower surface of said substrate; and

a bond wire electrically coupling said bond pad to said pin.

6. (withdrawn) The package of Claim 4 wherein said first electronic component comprises a first surface comprising a bond pad and a second surface coupled to said pocket base surface, said package further comprising:

an inner trace coupled to said pocket base surface;

a bond wire electrically coupling said bond pad to said inner trace; and

an outer trace coupled to a lower surface of said substrate, said inner trace being electrically coupled to said outer trace.

7. (withdrawn) The package of Claim 6 further comprising an interconnection pad coupled to said outer trace.

8. (withdrawn) The package of Claim 6 further comprising an interconnection ball coupled to said outer trace.

9. (currently amended) The package of Claim 4 13 wherein said sealing encapsulant comprises a cured flowable material.

10. (currently amended) The package of Claim 4 13 wherein said exterior surface of said sealing encapsulant has a smoothness approximate equal to a smoothness of glass.

11. (currently amended) The package of Claim 4 13 wherein said sealing encapsulant is opaque.

12. (currently amended) The package of Claim 4 13 wherein said excess encapsulant is formed of a same material as said sealing encapsulant.

13. (currently amended) A package comprising:
a substrate comprising:

a pocket;
an overflow reservoir around a periphery of said
pocket; and
a mating surface around a periphery of said overflow
reservoir;
a first electronic component coupled within said pocket;
a sealing encapsulant filling said pocket, said sealing
encapsulant comprising an exterior surface coplanar with said
mating surface; and
excess encapsulant within said overflow reservoir, The
~~package of Claim 1~~ wherein said excess encapsulant comprises an
exterior surface below said mating surface.

14. (currently amended) The package of Claim 1 13
wherein said substrate further comprises:

a pocket base surface;
a pocket sidewall surface, said pocket base surface and
said pocket sidewall surface defining said pocket;
a drain base surface;
a drain inner sidewall surface;
a drain outer sidewall surface, said drain base surface,
said drain inner sidewall surface, and said drain outer
sidewall surface defining said overflow reservoir; and
a runner surface extending between said drain inner
sidewall surface and said pocket sidewall surface.

15. (previously presented) The package of Claim 14
wherein said runner surface extends between said pocket and
said overflow reservoir.

16. (previously presented) The package of Claim 14
wherein said mating surface extends from said drain outer
sidewall surface.

17. (currently amended) A package comprising:
a substrate comprising:

a pocket;

a pocket base surface;

a pocket sidewall surface, said pocket base surface
and said pocket sidewall surface defining said pocket;

an overflow reservoir around a periphery of said
pocket;

a drain base surface;

a drain inner sidewall surface;

a drain outer sidewall surface, said drain base
surface, said drain inner sidewall surface, and said drain
outer sidewall surface defining said overflow reservoir;

a mating surface around a periphery of said overflow
reservoir and extending from said drain outer sidewall
surface; and

a runner surface extending between said drain inner
sidewall surface and said pocket sidewall surface, The
package of Claim 16 wherein said runner surface is below
said mating surface;

a first electronic component coupled within said pocket;

a sealing encapsulant filling said pocket, said sealing
encapsulant comprising an exterior surface coplanar with said
mating surface; and

excess encapsulant within said overflow reservoir.

18-32. (canceled)

33. (previously presented) The package of Claim 14
wherein said pocket base surface is below said drain base
surface.

34-35. (canceled)

36. (currently amended) A package comprising:
a substrate comprising:

a pocket;

an overflow reservoir around a periphery of said
pocket;

a runner surface extending between said pocket and
said overflow reservoir; and

a mating surface around a periphery of said overflow
reservoir;

a first electronic component coupled within said pocket;

a sealing encapsulant filling said pocket, said sealing
encapsulant extending over and above said runner surface; and
excess encapsulant within said overflow reservoir.

37. (currently amended) The package of Claim 36 wherein
said sealing encapsulant comprises an entirely planar exterior
surface extending over and above said runner surface.

38. (previously presented) The package of Claim 36
wherein said sealing encapsulant comprises an exterior surface,
said exterior surface comprising a planar central region and a
non-planar peripheral region.